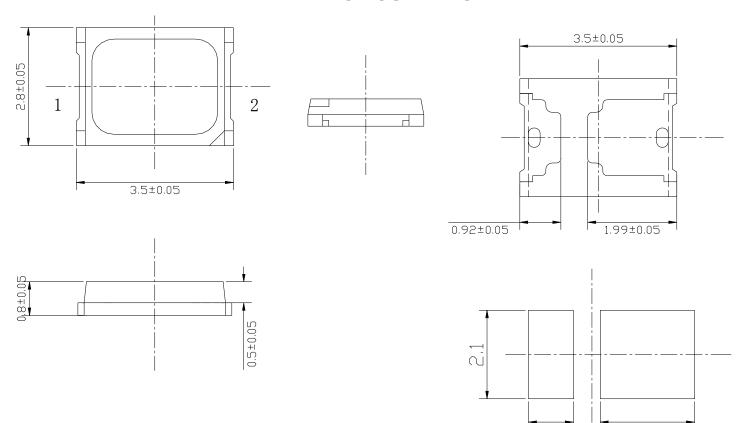


SPECIFICATION CSHF1311R2C

PACKAGE OUTLINES



Notes:

2

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSHF1311R2C	InGaAIP	Red	Water Clear	120°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	150	mA	
Reverse Current @ 5V	lR	10	μΑ	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfP	150	mA	
Soldering Temperature	TsoL	Max 260°C for	5 sec Max	

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Cymbol	Toot Condition	Value			Lloit
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 60mA	8	10	1	lm
Forward Voltage	VF	IF = 60mA	-	2.1	2.4	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μA
Viewing Angle at 50% Iv	201/2	IF = 60mA	-	120	-	Deg
Dominant Wavelength	λD	IF = 60mA	615	-	630	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.





OPTICAL CHARACTERISTIC CURVES

Fig.1-Forward Voltage Vs. Forward Current 伏安特性曲线

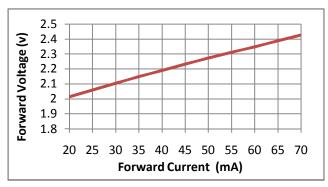


Fig.3-Ambient Temperature Vs. Relative Intensity 环境温度与相对光强特性曲线

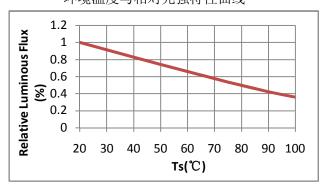


Fig.5-Forward Voltage Vs. Ambient Temperature 电压与环境温度特性曲线

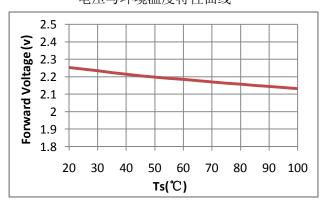
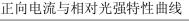


Fig.2-Forward Current Vs. Relative Intensity



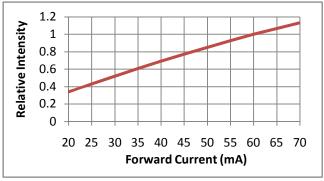


Fig.4-Ambient Temperature Vs. Forward Current 环境温度与正向电流特性曲

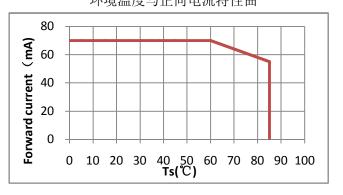
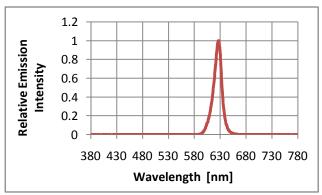


Fig.6- Spectrum Distribution

光谱分布特性曲线

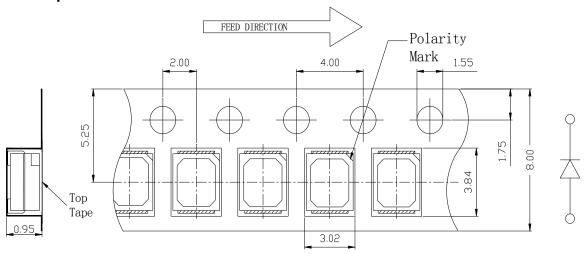


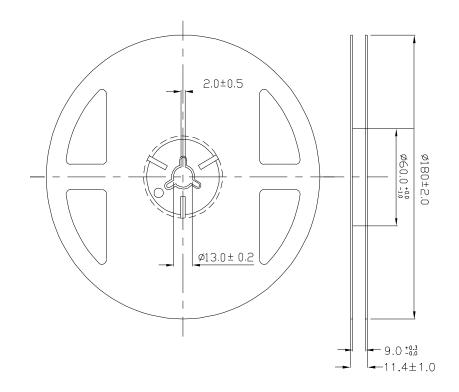




PACKAGING SPECIFICATION

■ Carrier Tape Dimensions





NOTES

- Empty component pockets are sealed with top cover tape;
 The maximum number of missing lamps is two;
 The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
- 4. 3,000 pcs/ Reel.





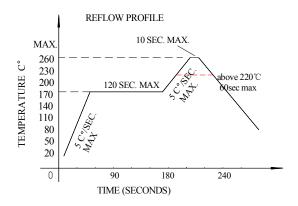
SOLDERING CONDITIONS

Reflow profile

- Soldering condition
 - Recommended soldering conditions

Reflow Soldering		Hand Soldering		
Pre-heat	160∼180℃	Temperature	300°C Max.	
Pre-heat time	120 seconds Max.			
Peak temperature	260°C Max.	Soldering time	3 second Max.	
Soldering time	10 seconds Max.		(one time only)	
Condition	Refer to Temperature-profile			

- · After reflow soldering rapid cooling should be avoided
- Temperature-profile (Surface of circuit board)
 Use the following conditions shown in the figure.



- 1. Reflow soldering should not be done more than two times
- 2. When soldering ,do not put stress on the LEDs during heating

■ Soldering iron

- 1. When hand soldering, keep the temperature of the iron under 300°C, and at that temperature keep the time under 3 sec.
- 2. The hand soldering should be done only a time
- 3. The basic spec is \leq 5 sec. when the temperature of 260°C, do not contact the resin when hand soldering

■ Rework

- 1. Customer must finish rework within 5 sec under 260°C
- 2. The head of iron can not touch the resin
- 3. Twin-head type is preferred.

